规格书编号

SPEC NO :

产品规格书
SPECIFICATION

CUSTOMER 客 户：

PRODUCT 产 品：**SAW FILTER**

MODEL NO 型 号：**HDBF07009B24**

PREPARED 编 制：　　CHECKED 审 核：Houshihong

APPROVED 批 准：CHARLES　　D A T E 日 期：2007-01-25

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司

Shoulder Electronics Limited

更改历史记录
History Record

更改日期 Date	规格书编号 Spec No	产品型号 Part No	客户产品型号 Customer No	更改内容描述 Modify Content	备注 Remark

1. SCOPE

This specification shall cover the characteristics of SAW filter with HDBF07009B24 used for the page system.

2. ELECTRICAL SPECIFICATION

DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-20℃ to +70℃
Storage temperature	-40℃ to +85℃
RF Power Dissipation	0dBm

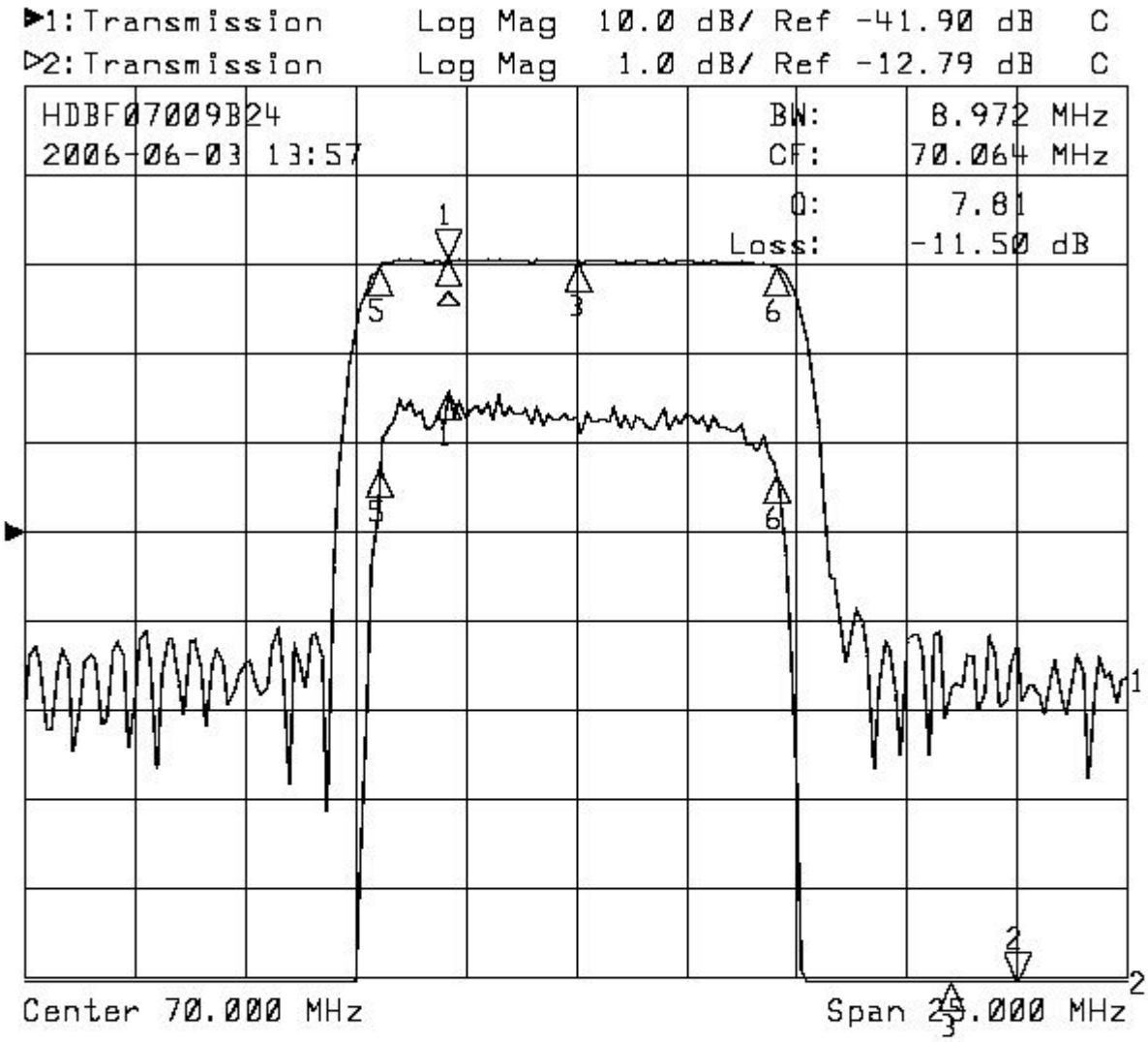
Electronic Characteristics

Fo = 70.0 MHz

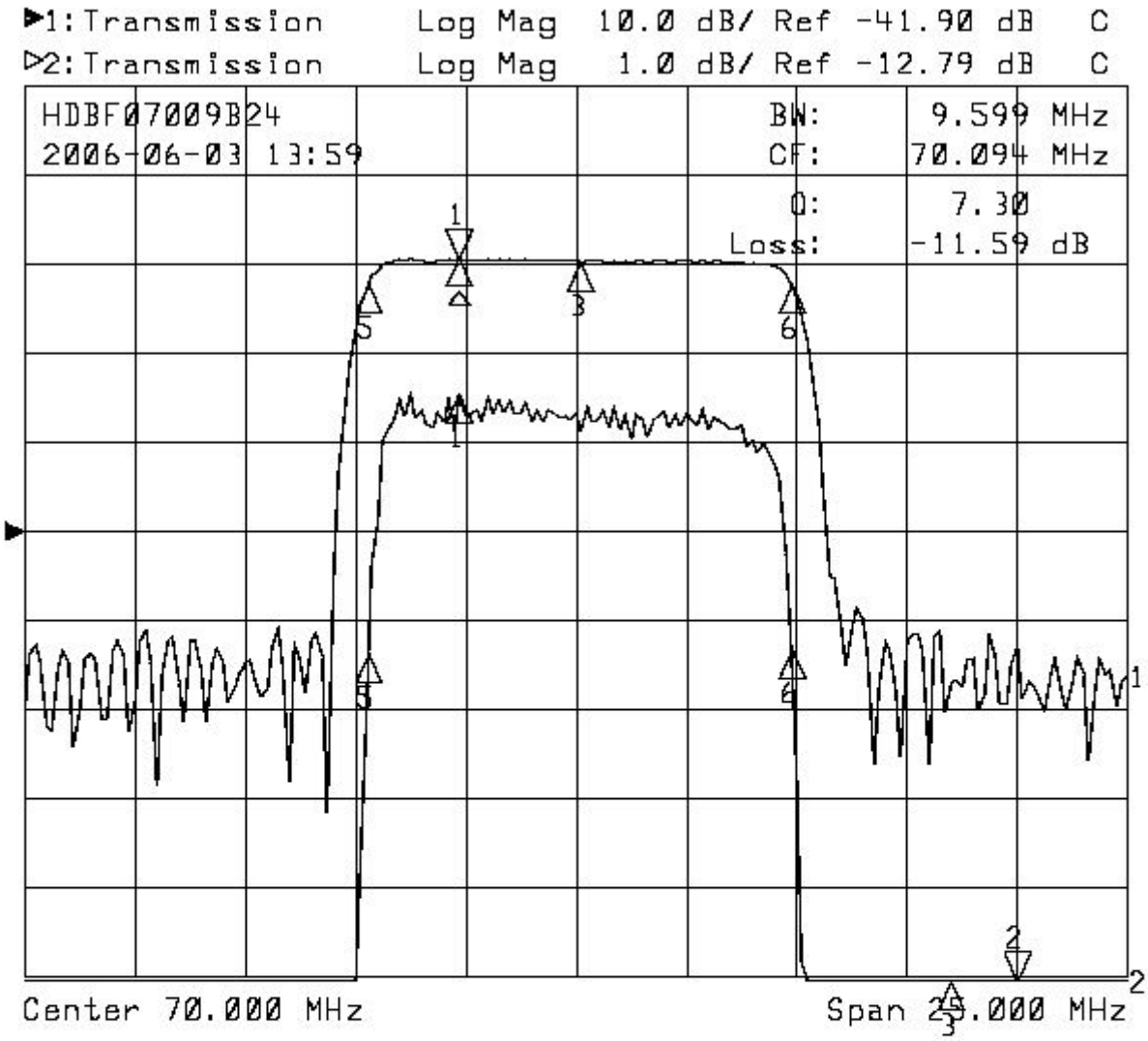
Terminating source impedance: 50 ohm and matching network

Terminating load impedance: 50 ohm and matching network

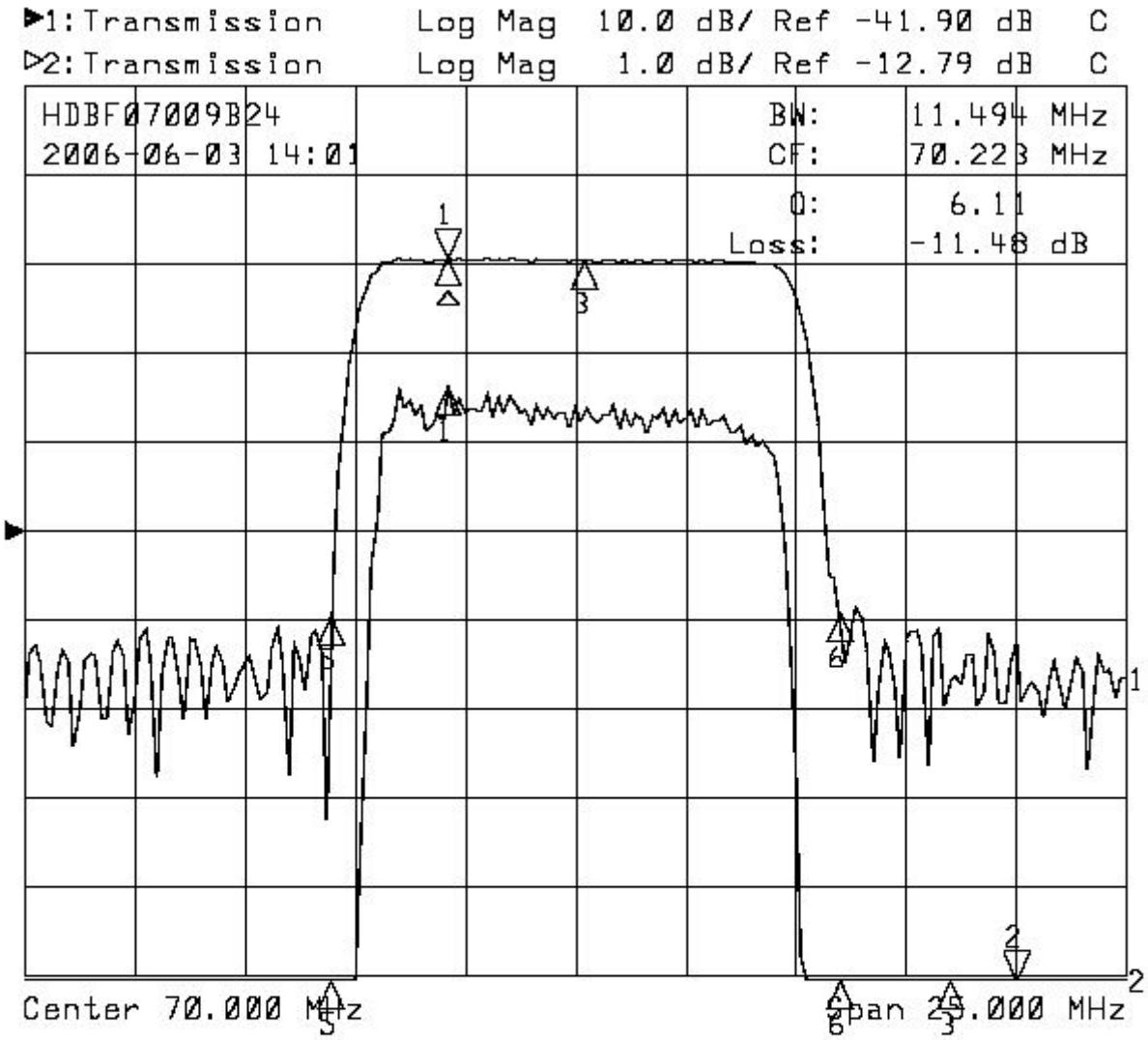
		Minimum	Typical	Maximum
Center Frequency	MHz	69.94	70.0	70.06
Insertion Loss	dB	-	11.5	12.5
1dB Bandwidth 3dB Bandwidth 40dB Bandwidth	MHz MHz MHz	8.7 9.4 -	9.0 9.53 11.5	- - 12.0
Amplitude Ripple (Fo +/- 4.375 MHz) Group Delay Variation (Fo +/- 4.375 MHz)	dB nsec	- -	0.8 100	1.2 150
Absolute Delay	usec	-	1.55	-
Ultimate Rejection	dB	38	45	-
Temperature Coefficient of Frequency	ppm/°C	-	-94	-



1:Mkr Δ(MHz)		dB	2:Mkr (MHz)	dB
1>	0.0000	0.000	1: 67.1250	-11.215
			2> 80.0000	-54.332
3:	2.9385	-0.377	3: 70.0635	-59.439
5:	-1.5648	-0.882	5: 65.5602	-12.069
6:	7.4243	-0.955	6: 74.5493	-12.132

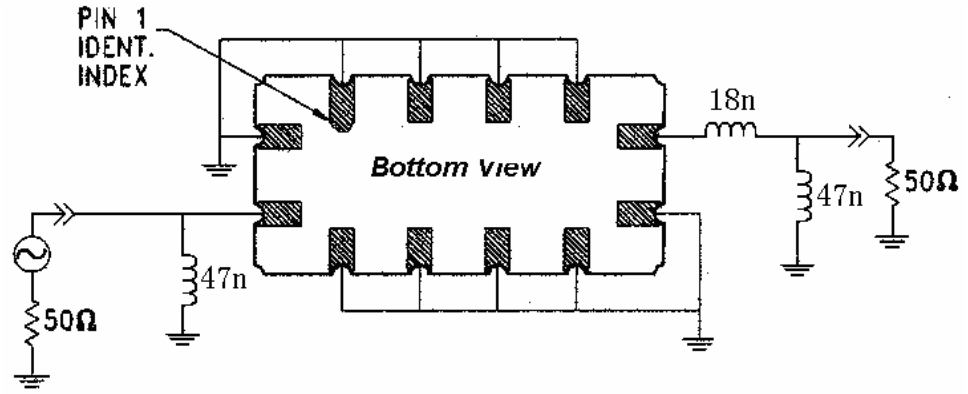


1: Mkr Δ(MHz)		dB	2: Mkr (MHz)		dB
1›	0.0000	0.000	1:	67.3750	-11.251
			2›	80.0000	-54.538
3:	2.7194	-0.344	3:	70.0944	-58.985
5:	-2.0800	-2.899	5:	65.2950	-14.161
6:	7.5187	-2.860	6:	74.8937	-14.121

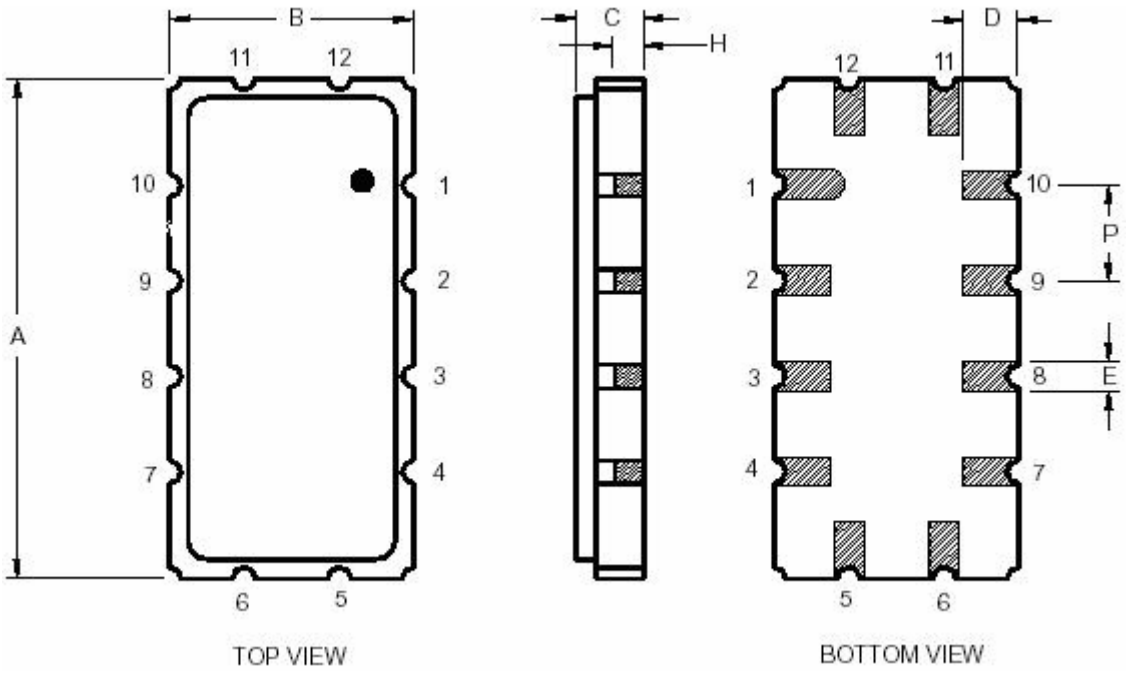


1:Mkr Δ(MHz)		dB	2:Mkr (MHz)	dB
1>	0.0000	0.000	1: 67.1250	-11.158
			2> 80.0000	-54.167
3:	3.0975	-0.297	3: 70.2225	-58.774
5:	-2.6497	-40.292	5: 64.4753	-51.438
6:	8.8448	-40.057	6: 75.9698	-51.190

3. TEST CIRCUIT



4.DIMENSION



Pin Configuration	
11	Input
5	Output
Other	Ground

Dimension	mm		
	min	typ	max
A	13.1	13.3	13.5
B	6.3	6.5	6.7
C	1.21	1.36	1.51
D		1.5	
E		0.8	
H	0.72	0.76	0.80
P		2.54	

5. ENVIRONMENTAL CHARACTERISTICS

5-1 Temperature cycling

Subject the device to a low temperature of -40℃for 30 minutes. Following by a high temperature of +25℃ for 5 Minutes and a higher temperature of +85℃ for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in table 1.

5-2 Resistance to solder heat

Submerge the device terminals into the solder bath at 260℃ ±5℃ for 10±1 sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in table 1.

5-3 Solderability

Submerge the device terminals into the solder bath at 245℃ ±5℃ for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in table 1.

5-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in table 1.

5-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in table 1.

6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration &destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.